

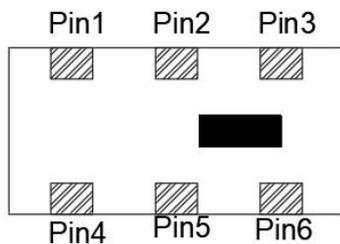
Features

- Multilayer monolithic construction yields high reliability
- Low insertion loss and small size SMD chip design
- Can simplify your complex tuning and circuit design
- LTCC process

Specifications

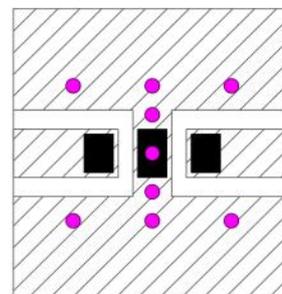
NO.	Parameter	SPEC
1	Frequency range	3300~3800 MHz
2	Insertion Loss	0.6 dB max. at +25°C
3	Attenuation	35 dB min. @ 6600~7600 MHz 35 dB min. @ 9900~11400 MHz
4	VSWR (In BW)	2.0 max.
5	Port Impedance	50Ω
6	Power	3W max.
7	Operation Temperature Range	-40°C ~ +85°C

Construction



PIN	Connection
1	GND
2	Input port
3	GND
4	GND
5	Output port
6	GND

Mounting Considerations

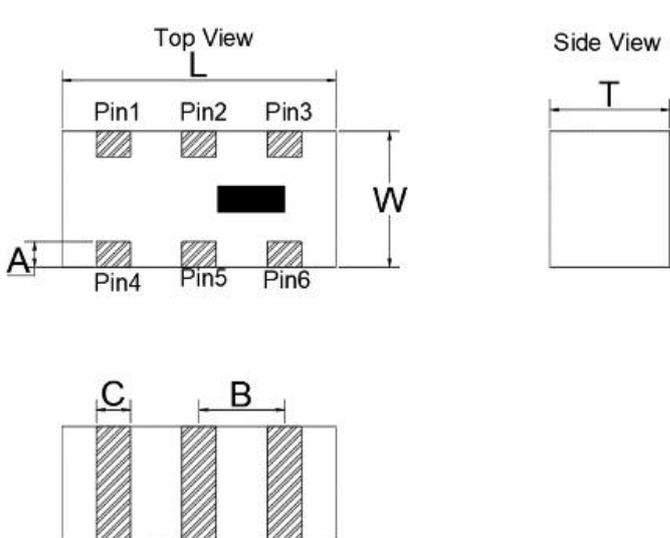


- Land
- ▨ Solder
- Through-hole

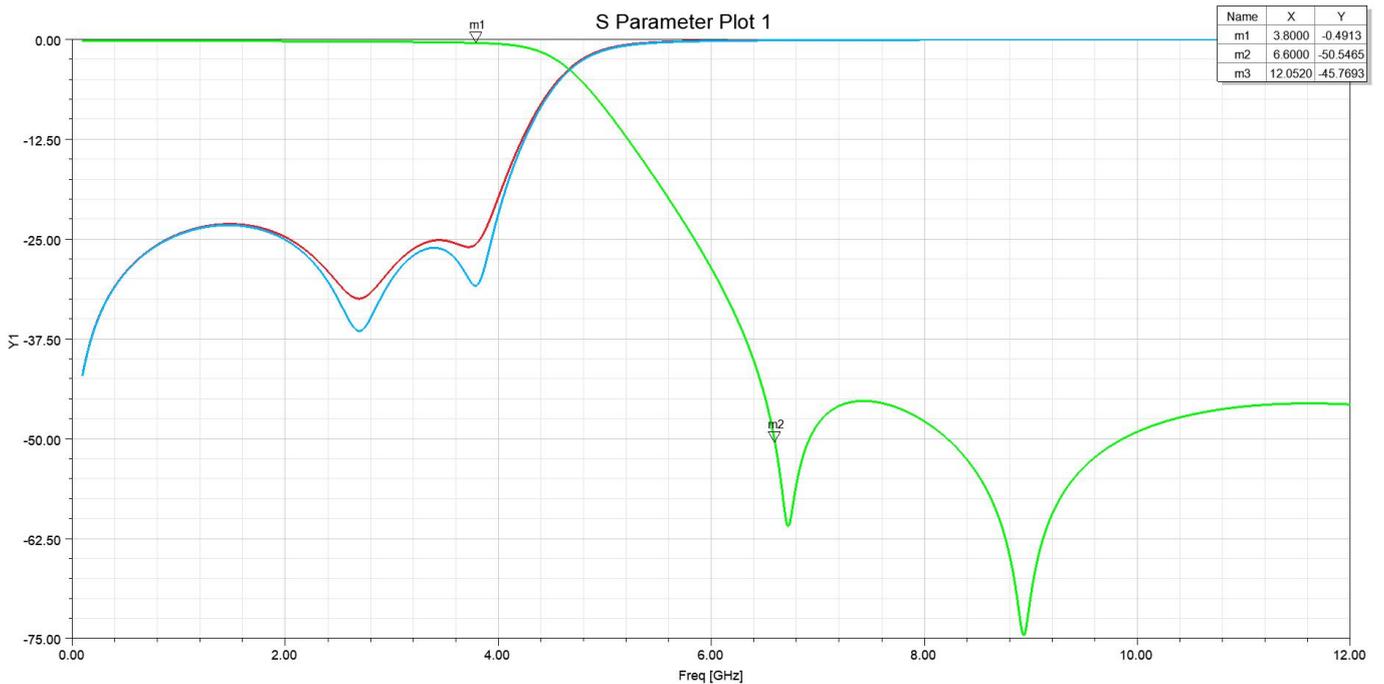
Unit: mm

Line width to be designed to match 50 Ω characteristic impedance, depending on PCB material and thickness

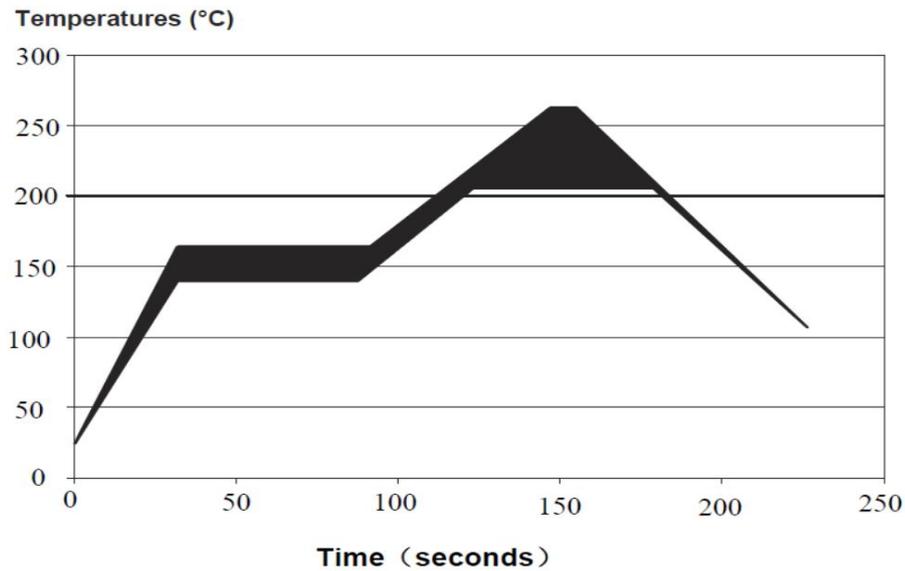
Dimensions

Figure	Symbol	Dimension (mm)
	L	1.6 ± 0.10
	W	0.8 ± 0.10
	T	0.6 ± 0.10
	A	0.15 ± 0.10
	B	0.55 ± 0.10
	C	0.30 ± 0.10

Typical Electrical Characteristics (T=25°C)



Solder Reflow Standard Conditioning



Storage Conditions

Temperature : +5 to +30 °C

Humidity : 20 to 70% RH

Term of storage : Within 12 months (After the delivery) *

Baking : Unnecessary

* After peeling off cover tape, do not keep exposing the products to the open air. For the products stored longer than 12 months, confirm their terminals and solderability before use.